

Integrated Power Management/Audio Codec

FEATURES

- **Power**
 - Three Efficient Stepdown Converters
 - Ten External Linear Low-Dropout Regulators (LDOs) for Clocks and Peripherals
 - SmartReflex™ Dynamic Voltage Management
- **Audio**
 - Voice Codec
 - 15-Bit Linear Codec (8 kHz/16 kHz)
 - Differential Input Main and Submicrophones
 - Differential Headset Microphone Input
 - Auxiliary/FM Input (Mono or Stereo)
 - Differential 32-Ω Speaker and 16-Ω Headset Drivers (External Predrivers for Class-D)
 - 8-Ω Stereo Class D Drivers
 - PCM and TDM Interfaces
 - Bluetooth® Interface
 - Automatic Level Control (ALC)
 - Digital and Analog Mixing
 - 16-bit Linear Audio Stereo DAC (96 kHz, 48 kHz, 44.1 kHz, 32 kHz, and Derivatives)
 - 16-Bit Linear Audio Stereo Analog-to-Digital (ADC) (48 kHz, 44.1 kHz, 32 kHz, and Derivatives)
 - Digital Microphone Inputs
 - Carkit
- **Charger**
 - Li-ion, Li-polymer, and Manganese-Cobalt Charger
 - Supports Charging With AC Regulated Charger (Maximum 7 V), USB Host Devices, MCPC Devices, USB Chargers, and Car Kit Chargers (Maximum 7V)
 - Backup Battery Charger
- **USB**
 - USB 2.0 OTG-Compliant High-Speed Transceivers
 - 12-Bit (UTMI) + Low Pin Interface (ULPI)
 - USB Power Supply (5V charge pump for VBUS)
 - CEA-2011: OTG Transceiver Interface Specification
 - CEA-936A: Mini-USB Analog Carkit Specification
 - MCPC ME-UART GL-006 Specification
- **Additional**
 - LED Driver Circuit for Two External LEDs
 - 10-Bit Monitoring ADC With 3 to 8 External Inputs
 - Real-Time Clock (RTC) and Retention Modules
 - High-Speed I²C Serial Control
 - Thermal Shutdown and Hot-Die Detection
 - Keypad Interface (up to 8 × 8)
 - External Vibrator Control
 - 18 GPIOs
 - 0,4 mm Pitch, 209 Pin, 7 × 7 mm Package



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PRODUCT PREVIEW

In addition to generic support capabilities, the TPS65950 meets the specific power requirements of the TI OMAPV1230, OMAP2430C, and OMAP3430 devices.



Figure 1. Block Diagram

MODULE DESCRIPTION

Power subchip:

The SMPS have configurable output voltages. The LDO regulators provide power to internal analog and digital circuits and to the external components. The output voltages of the external LDOs are also configurable.

The power resources also have configurable modes of operation. The possible modes for the power resources are SLEEP, ACTIVE, and OFF. The modes and output values can be programmed using the I2C interface on the TPS65950 device.

Programming for all the power resources is done through the I2C interface. The power subchip interfaces the interface subchip and carries out commands to the rest of the device. The digital section has a finite state-machine (FSM) that manages commands to the resources through the power bus.

Audio subchip:

The audio subchip has two interfaces: PCM for voice signaling and I2S for audio signaling. The Bluetooth interface is also available. This uses the same clock and sync signals as for the PCM interface. Both ports can function as master or slave.

Sampling modes available are:

Voice channel with 8-kHz or 16-kHz sampling modes

Audio channel with 8, 11.025, 12, 16, 22.05, 24, 32, 44.1, or 48-kHz sampling modes. 96 kHz is supported on the RX path voice codec with MCLK = 26MHz.

The audio phase-locked loop (PLL) supports 26-MHz, 19.2-MHz, or 38.4-MHz ability to work with two ports with the clock frequencies 19.2 MHz or 26 MHz, or with a single TDM port with the frequencies 19.2 MHz, 26 MHz, or 38.4 MHz. The voice PCM interface is available when the system clock is 26MHz.

The audio supports common features like pop-noise reduction, sidetone functionality, bass boost function, uplink and downlink programmable gain amplifiers, and the DTMF tone generator.

The external vibrator control is provided in this module and can be controlled through an audio signal or direct I2C writes to the registers.

USB subchip:

The primary function of the universal serial bus (USB) physical layer (PHY) is to transmit and receive USB data at high speed (480M bit/s), full speed (12M bit/s), and low speed (1.5M bit/s). It also provides a pin-optimized standard ULPI interface to a main USB controller device (LINK). In addition to the higher speeds, it supports 3-pin and 4-pin serial modes of operation.

The TPS65950 has a 5V-tolerant data line at all supported speeds. VBUS is tolerant up to 6 V. This device has an on-chip 480MHz PLL from the internal system clock.

Auxiliary subchip:

The auxiliary subchip includes the following modules:

- Monitoring Analog-to-Digital Conversion (MADC)
- Battery Charger Interface (BCI)
- LED
- Keypad

MADC:

The MADC enables the host processors to monitor analog signals (such RF module temperature, battery temperature, battery type, and battery level) using analog-to-digital conversion (ADC) on the input source. After the conversion is complete, the host processor reads the results of the conversion through the I2C interface. The MADC also performs analog signal conversion for other modules in the TPS65950: the BCI and the USB subchip.

BCI:

The BCI can perform software-controlled linear charging with all the chargers it supports. The BCI can perform software-controlled pulsed charging with current-limited ac chargers and automatic linear charging with ac chargers, USB chargers, and carkits.

The magnitudes of the charging current and the charging voltage are set by 10 bits of a programming register converted by a 10-bit digital-to-analog converter (DAC) whose output sets the reference input of the charging current and the charging voltage-control loop.

The BCI can perform monitoring functions like ac charger detection, VBUS detection, battery detection, ac charger overvoltage detection, VBUS overvoltage detection, battery overvoltage detection, battery charge current level detection, battery voltage level detection, battery temperature out-of-range detection, battery end-of-charge detection and battery over current detection.

Keypad:

The keypad controller supports up to 8×8 keypad matrix. The keypad includes an integrated programmable timer for debounce, long key press, and time-out events. It supports programmable interrupt generation on key events, multikey press detection and decoding, and long key detection on prolonged key press.

The keypad can be used in software scanning mode or hardware decoding mode.

LED:

The TPS65950 device provides light-emitting diode (LED) driver circuitry to power two LED (dc power) circuits that can illuminate a panel or provide user indicators. The two circuits (LEDA and LEDB) are identical except for their current capabilities: LEDA is rated for 160 mA and LEDB is rated for 60 mA.

Interface subchip:

The interface subchip is the main interface between the external components and the TPS65950 device. This module includes the primary and secondary interrupt handlers that generate interrupts and provide them to the host processor for further action. Two interrupt lines can be routed to external hosts. The device provides the interrupt mapping to track down the interrupt originator. Each subchip has several interrupts that get mapped on to the external interrupts.

The device handles all I2C communication with the external host processors, and internal communication is managed by the OCP (Open Core Protocol) standard. This also includes the GPIOs.

PACKAGING INFORMATION

Package Thermal Resistance Characteristics

[Table 1](#) lists the thermal resistance characteristics for the recommended package types used on the TPS65950 device.

Table 1. TPS65950 Thermal Resistance Characteristics

PACKAGE	R _{θJA} (C/W)	R _{θJB} (C/W)	R _{θJC} (C/W)	BOARD TYPE
TPS65950	38.4	15.2	19.2	1S2P ⁽¹⁾
TPS65950	56.5	15.5	19.2	1S0P ⁽¹⁾

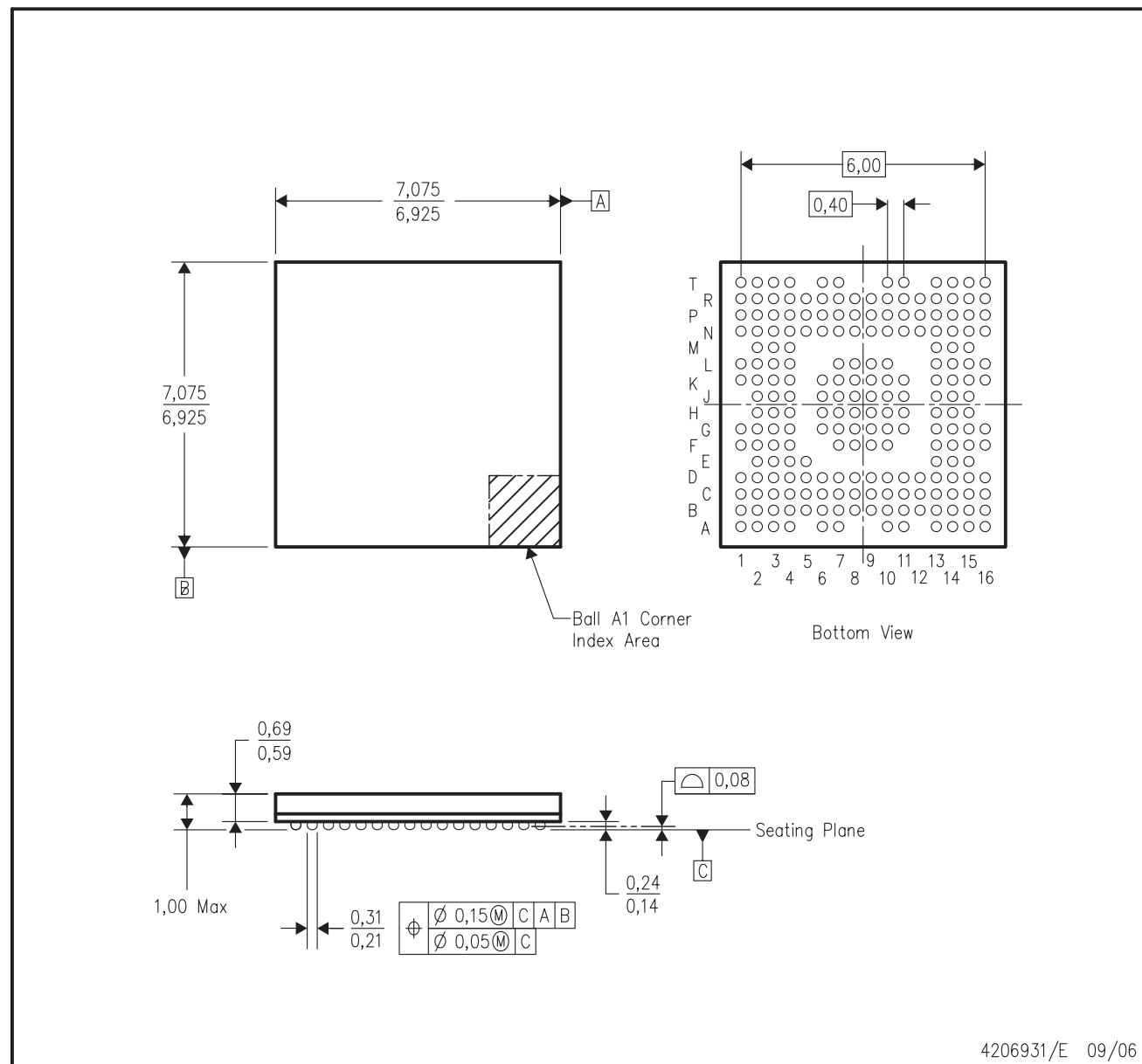
(1) The board types are defined by JEDEC (reference JEDEC standard JESD51-9, Test Board for Area Array Surface Mount Package Thermal Measurements).

Mechanical Data

Figure 2, Figure 3, and Figure 4 show the TPS65950 mechanical package.

ZXN (S–PBGA–N209)

PLASTIC BALL GRID ARRAY

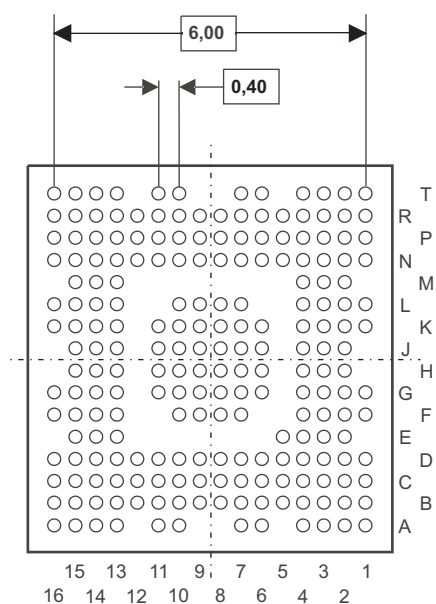


PRODUCT PREVIEW

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
 - B. This drawing is subject to change without notice.
 - C. This is a lead-free solder ball design.

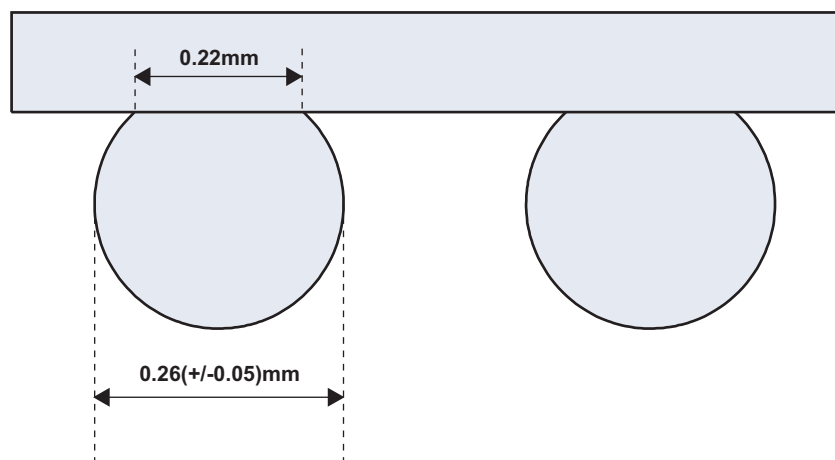
034-002

Figure 2. TPS65950 Mechanical Package



034-003

Figure 3. TPS65950 Mechanical Package -- Top View



034-004

Figure 4. TPS65950 Ball Size

GLOSSARY

TERM	MEANING
DTMF	Dual Tone Multi-Frequency Sixteen pairs of audio tones developed when telephones in the United States evolved from rotary to push-button dialing.
GPIO	General Purpose Input/Output Input and output port of a device that has no dedicated purpose and so is available for general applications.
PCM	Pulse Code Modulation The process of representing a signal by a sequence of pulses. Two commonly used forms of PCM are pulse-width modulation (PWM) and pulse-frequency modulation (PFM).
SMPS	Switched Mode Power Supply A power supply in which the output is being turned on and off at a rapid rate and the output voltage is controlled by changing the duty cycle; that is, the percentage of time it is turned on compared to the amount of time it is turned off. The desired dc output is obtained from the SMPS by use of a filtering network that converts the switched output to its averaged value. The output of a SMPS is fully on or off; it is not partially on or off as is true of a linear power supply.
TDM	Time Division Multiplex The technique used to put multiple digital signals onto the same path by assigning each signal its own time slot.

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